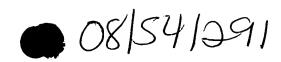
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Serial No.:

Inventor(s): Farnworth et al.

## BONDPAD ATTACHMENTS USED TO TEMPORARILY CONNECT SEMICONDUCTOR DIE

## ABSTRACT

A die contacting substrate establishes ohmic contact with the die by means of raised portions on contact members. The raised portions are dimensioned so that a compression force applied to the die against the substrate results in a limited penetration of the contact member into the bondpads. The arrangement may be used for establishing electrical contact and with a burn-in oven and with a discrete die tester. This permits the die to be characterized prior to assembly, so that the die may then be transferred in an unpackaged form. A Z-axis anisotropic conductive interconnect material may be interposed between the die attachment surface and the die.

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